2SK2326

Silicon N-Channel Power F-MOS FET

■ Features

- Avalanche energy capacity guaranteed
- High-speed switching
- Low ON-resistance
- No secondary breakdown

■ Applications

- Contactless relay
- Diving circuit for a solenoid
- Driving circuit for a motor
- Control equipment
- Switching power supply

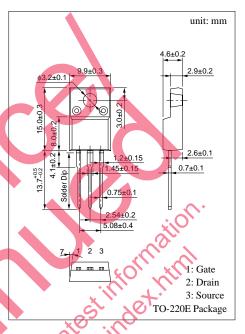
■ Absolute Maximum Ratings (T_C = 25°C)

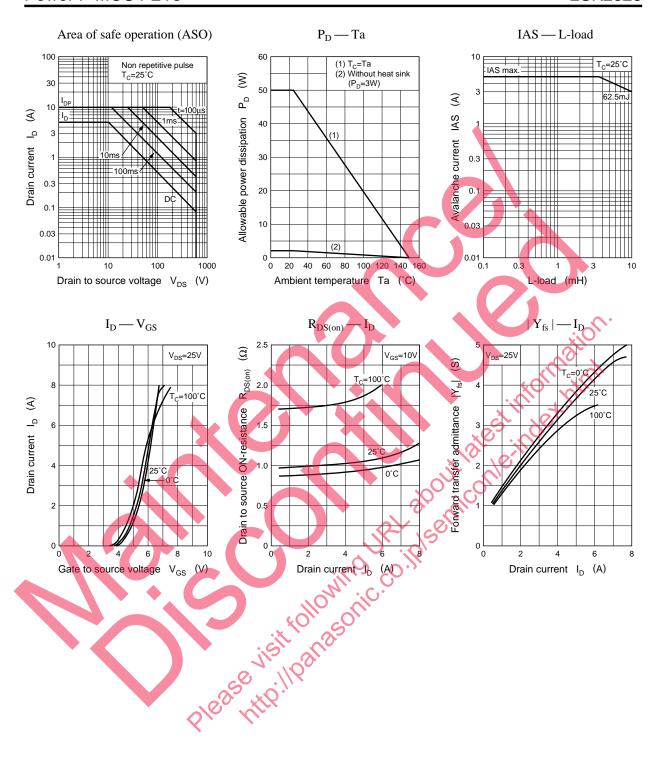
Parameter		Symbol	Ratings	Unit	
Drain to Source breakdown voltage		V _{DSS}	600	V	
Gate to Source voltage		V _{GSS}	±30	V	
Drain current	DC	I_D	±5	A	
	Pulse	I_{DP}	±10	A	
Avalanche energy capacity		EAS*	62.5	mJ	
Allowable power	$T_C = 25^{\circ}C$	D	50	W	
dissipation $Ta = 25^{\circ}C$		P_{D}	2	***	
Channel temperature		T_{ch}	150	°C	
Storage temperature	$T_{\rm stg}$	-55 to +150	°C		

^{*} L = 5mH, $I_L = 5A$, 1 pulse

■ Electrical Characteristics (T_C = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I_{DSS}	$V_{DS} = 480V, V_{GS} = 0$			100	μΑ
Gate to Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0$			±1	μΑ
Drain to Source breakdown voltage	$V_{\rm DSS}$	$I_D = 1 \text{mA}, V_{GS} = 0$	600			V
Gate threshold voltage	V _{th}	$V_{\rm DS} = 25 \text{ V}, I_{\rm D} = 1 \text{ mA}$	2		5	V
Drain to Source ON-resistance	R _{DS(on)}	$V_{GS} = 10V$, $I_D = 3A$		1	1.5	Ω
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 25V, I_D = 3A$	1.7	2.8		S
Diode forward voltage	V_{DSF}	$I_{DR} = 5A, V_{GS} = 0$			-1.6	V
Input capacitance (Common Source)	C _{iss}			1300		pF
Output capacitance (Common Source)	Coss	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$		130		pF
Reverse transfer capacitance (Common Source)	C_{rss}			40		pF
Turn-on time (delay time)	$t_{d(on)}$			20		ns
Rise time	t _r	$V_{DD} = 200V, I_D = 3A$		35		ns
Fall time	$t_{\rm f}$	$V_{GS} = 10V, R_L = 66.6\Omega$		50		ns
Turn-off time (delay time)	t _{d(off)}			150		ns
Thermal resistance between channel and case	R _{th(ch-c)}				2.5	°C/W
Thermal resistance between channel and atmosphere	R _{th(ch-a)}				62.5	°C/W





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